

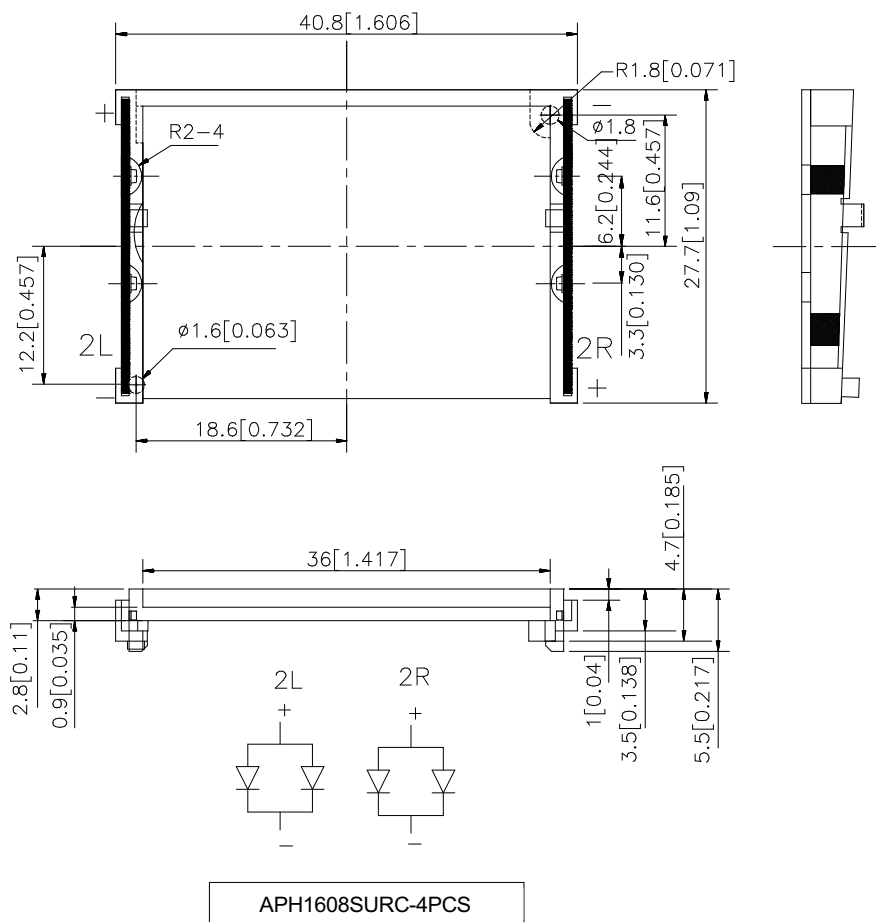
### Features

- LOW POWER REQUIREMENTS.
- LARGE AREA, UNIFORM, BRIGHT LIGHT EMITTING SURFACE.
- EASY FOR INSTALLATION.
- LOW POWER CONSUMPTION.

### Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

### Package Dimensions & Internal Circuit Diagram



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25$  (0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Ev (lux) @ 80mA	
			Min.	Typ.
GLP003/1608SURC	HYPER RED (InGaAlP)	WATER CLEAR	69	103

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

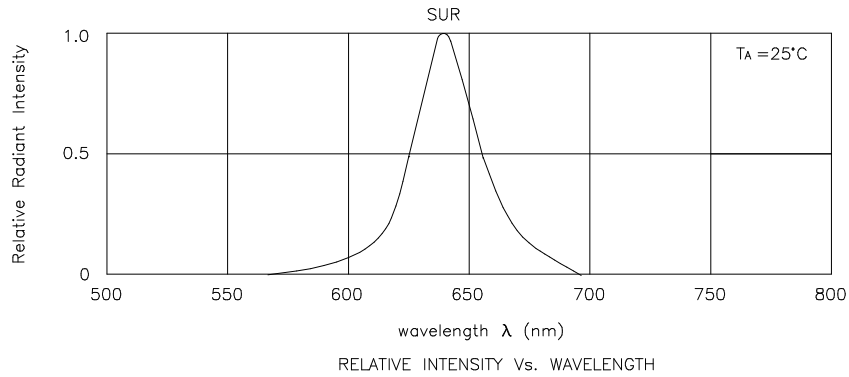
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Hyper Red	640	--	nm	I <sub>F</sub> =20mA(per chip)
$\lambda_D$	Dominate Wavelength	Hyper Red	628	--	nm	I <sub>F</sub> =20mA(per chip)
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red	27	--	nm	I <sub>F</sub> =20mA(per chip)
C	Capacitance	Hyper Red	45	--	pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Hyper Red	1.9	2.5	V	I <sub>F</sub> =20mA(per chip)
I <sub>R</sub>	Reverse Current	Hyper Red	--	10	uA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Hyper Red	Units
Power dissipation	245	mW
Forward Current	120	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

1. The Chips are four parallel.



## Hyper Red

### GLP003/1608SURC

